



Final Product Change Notification

201308016F01

Issue Date: 14-Dec-2013
Effective Date: 14-Mar-2014

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Change Category

- | | | | |
|--|--|---|--|
| <input type="checkbox"/> Wafer Fab process | <input type="checkbox"/> Assembly Process | <input type="checkbox"/> Product Marking | <input type="checkbox"/> Design |
| <input type="checkbox"/> Wafer Fab materials | <input checked="" type="checkbox"/> Assembly Materials | <input type="checkbox"/> Electrical spec./Test coverage | <input type="checkbox"/> Mechanical Specification |
| <input type="checkbox"/> Wafer Fab location | <input type="checkbox"/> Assembly Location | <input type="checkbox"/> Test Location | <input type="checkbox"/> Packing/Shipping/Labeling |

Change of bond wire material from Au to Cu and release of 2nd source mold compound

Details of this Change

Scheduled changes affect product types in SOD323 package only.

- (1) The bond wire material will be changed from gold to copper. Implementation of change to copper wire as given by implementation date below. Gold wire remains qualified for supply security reasons only.
- (2) A second source mold compound supplier will be introduced.

Old product: Wire material is gold (Au), mold compound suppliers are Henkel and Panasonic

Changed product: Wire material is copper (Cu) or gold (Au), mold compound suppliers for copper wire products are Henkel and Sumitomo

The design and materials of all other components will remain unchanged: Die, die attach and lead frame. Reliability qualification and full electrical characterization over temperature have been performed. No change on thermal behavior or mechanical dimensions. Electrical parameters remain unchanged (in specification and with the same distribution).

Why do we Implement this Change

- (1) Aligning with world technology standards, NXP continues to introduce copper wire for plastic SMD packages.

Copper wire shows enhanced mechanical properties.

(2) Following NXP company policy of second source material availability, Sumitomo mold compound will be added to the BOM. Sumitomo is already a well established mold compound supplier for NXP GA discrete semiconductor products.

Identification of Affected Products

Changed products can be identified by date code after implementation.

Product Availability

Sample Information

Samples are available upon request

Latest sample request date for PCN samples is 10-Jan-2014

Production

Planned first shipment 06-Mar-2014

Impact

No impact to the product's functionality.

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Existing inventory will be shipped until depleted

Timing and Logistics

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 13-Jan-2014.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please [contact NXP "Global Quality Support Team"](#).

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name	GA Customer Support
e-mail address	DiscrQA.Helpdesk.GA-Products@nxp.com

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NXP Quality Management Team.

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